# **Complementary Silicon Plastic Power Transistors**

## **DPAK-3** for Surface Mount Applications

Designed for low voltage, low-power, high-gain audio amplifier applications.

#### **Features**

- High DC Current Gain
- Lead Formed for Surface Mount Applications in Plastic Sleeves (No Suffix)
- Straight Lead Version in Plastic Sleeves ("-1" Suffix)
- Low Collector-Emitter Saturation Voltage
- High Current-Gain Bandwidth Product
- Annular Construction for Low Leakage
- Epoxy Meets UL 94 V-0 @ 0.125 in
- NJV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

## **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CB</sub>	100	Vdc
Collector-Emitter Voltage	V <sub>CEO</sub>	100	Vdc
Emitter-Base Voltage	V <sub>EB</sub>	7.0	Vdc
Collector Current – Continuous	I <sub>C</sub>	4.0	Adc
Collector Current – Peak	I <sub>CM</sub>	8.0	Adc
Base Current	I <sub>B</sub>	1.0	Adc
Total Device Dissipation  @ T <sub>C</sub> = 25°C  Derate above 25°C	P <sub>D</sub>	12.5 0.1	W W/°C
Total Device Dissipation  @ T <sub>A</sub> = 25°C (Note 2)  Derate above 25°C	P <sub>D</sub>	1.4 0.011	W W/°C
Operating and Storage Junction Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-65 to +150	°C
ESD – Human Body Model	HBM	3B	V
ESD – Machine Model	MM	С	V

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. When surface mounted on minimum pad sizes recommended.

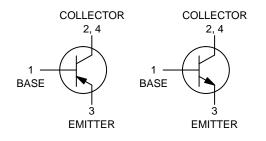


## ON Semiconductor®

http://onsemi.com

## 4.0 A, 100 V, 12.5 W POWER TRANSISTOR

#### COMPLEMENTARY





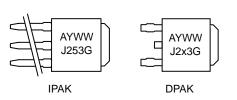


**CASE 369C** 

STYLE 1

CASE 369D STYLE 1

#### MARKING DIAGRAMS



= Assembly Location = Year

WW = Work Week = 4 or 5

= Pb-Free Package

## **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

## THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance Junction-to-Case Junction-to-Ambient (Note 2)	R <sub>θJC</sub> R <sub>θJA</sub>	10 89.3	°C/W

<sup>2.</sup> When surface mounted on minimum pad sizes recommended.

## **ELECTRICAL CHARACTERISTICS** (T<sub>C</sub> = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS	•			•
Collector–Emitter Sustaining Voltage (Note 3) $(I_C = 10 \text{ mAdc}, I_B = 0)$	V <sub>CEO(sus)</sub>	100	_	Vdc
Collector Cutoff Current $(V_{CB} = 100 \text{ Vdc}, I_E = 0)$ $(V_{CB} = 100 \text{ Vdc}, I_E = 0, T_J = 125^{\circ}\text{C})$	I <sub>CBO</sub>	- -	100 100	nAdc μAdc
Emitter Cutoff Current (V <sub>BE</sub> = 7.0 Vdc, I <sub>C</sub> = 0)	I <sub>EBO</sub>	_	100	nAdc
DC Current Gain (Note 3) ( $I_C = 200 \text{ mAdc}$ , $V_{CE} = 1.0 \text{ Vdc}$ ) ( $I_C = 1.0 \text{ Adc}$ , $V_{CE} = 1.0 \text{ Vdc}$ )	h <sub>FE</sub>	40 15	180 -	-
Collector–Emitter Saturation Voltage (Note 3) $(I_C = 500 \text{ mAdc}, I_B = 50 \text{ mAdc})$ $(I_C = 1.0 \text{ Adc}, I_B = 100 \text{ mAdc})$	V <sub>CE(sat)</sub>	- -	0.3 0.6	Vdc
Base–Emitter Saturation Voltage (Note 3) (I <sub>C</sub> = 2.0 Adc, I <sub>B</sub> = 200 mAdc)	V <sub>BE(sat)</sub>	-	1.8	Vdc
Base–Emitter On Voltage (Note 3) (I <sub>C</sub> = 500 mAdc, V <sub>CE</sub> = 1.0 Vdc)	V <sub>BE(on)</sub>	-	1.5	Vdc
DYNAMIC CHARACTERISTICS	·		•	
Current–Gain – Bandwidth Product (Note 4) (I <sub>C</sub> = 100 mAdc, V <sub>CE</sub> = 10 Vdc, f <sub>test</sub> = 10 MHz)	f⊤	40	_	MHz
Output Capacitance (V <sub>CB</sub> = 10 Vdc, I <sub>E</sub> = 0, f = 0.1 MHz)	C <sub>ob</sub>	_	50	pF

<sup>3.</sup> Pulse Test: Pulse Width = 300  $\mu$ s, Duty Cycle  $\approx$  2%. 4. f<sub>T</sub> = |h<sub>FE</sub>| • f<sub>test</sub>.

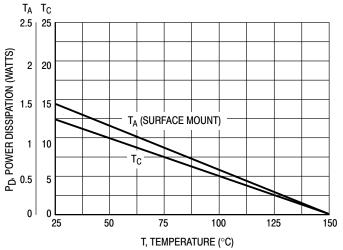


Figure 1. Power Derating

There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate  $I_C - V_{CE}$  limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

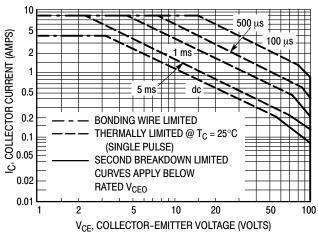


Figure 2. Active Region Maximum Safe Operating Area

The data of Figure 2 is based on  $T_{J(pk)} = 150^{\circ}C$ ;  $T_C$  is variable depending on conditions. Second breakdown pulse limits are valid for duty cycles to 10% provided  $T_{J(pk)} \le 150^{\circ}C$ .  $T_{J(pk)}$  may be calculated from the data in Figure 3. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.

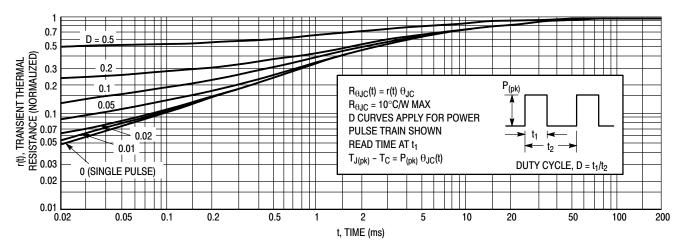


Figure 3. Thermal Response

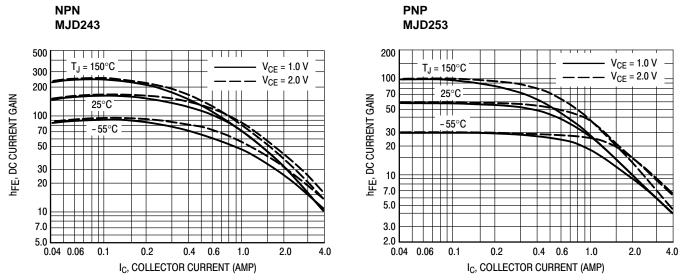


Figure 4. DC Current Gain

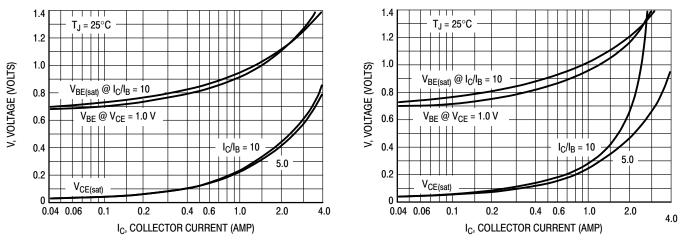
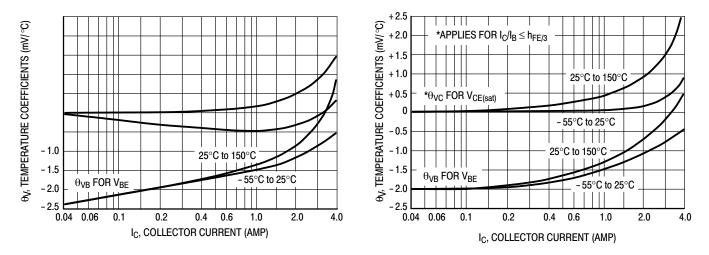
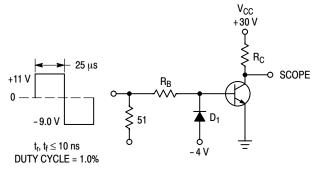


Figure 5. "On" Voltages



**Figure 6. Temperature Coefficients** 



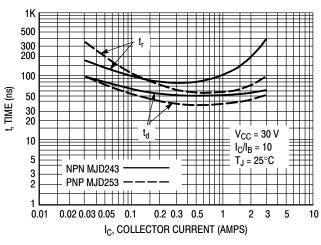


Figure 8. Turn-On Time

Figure 7. Switching Time Test Circuit

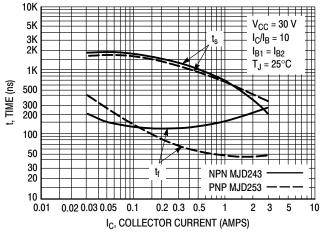


Figure 9. Turn-Off Time

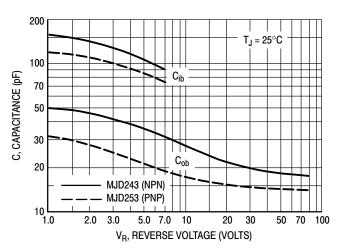


Figure 10. Capacitance

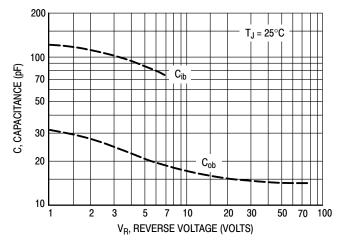


Figure 11. Capacitance

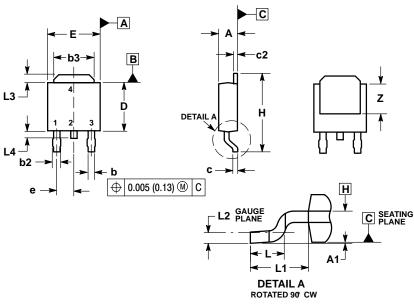
## **ORDERING INFORMATION**

Device	Package Type	Package	Shipping <sup>†</sup>
MJD243G	DPAK-3 (Pb-Free)	369C	75 Units / Rail
MJD243T4G	DPAK-3 (Pb-Free)	369C	2,500 / Tape & Reel
NJVMJD243T4G*	DPAK-3 (Pb-Free)	369C	2,500 / Tape & Reel
MJD253-1G	IPAK (Pb-Free)	369D	75 Units / Rail
MJD253T4G	DPAK-3 (Pb-Free)	369C	2,500 / Tape & Reel
NJVMJD253T4G*	DPAK-3 (Pb-Free)	369C	2,500 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
\*NJV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q101 Qualified and PPAP

### **PACKAGE DIMENSIONS**

### DPAK-3 CASE 369C ISSUE D



- NOTES:

  1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

  2. CONTROLLING DIMENSION: INCHES.

  3. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS b3, L3 and Z.

  4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.

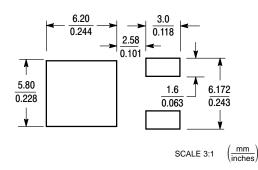
  5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.

  6. DATUMS A AND B ARE DETERMINED AT DATUM PLANE I.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.086	0.094	2.18	2.38
A1	0.000	0.005	0.00	0.13
b	0.025	0.035	0.63	0.89
b2	0.030	0.045	0.76	1.14
b3	0.180	0.215	4.57	5.46
С	0.018	0.024	0.46	0.61
c2	0.018	0.024	0.46	0.61
D	0.235	0.245	5.97	6.22
Е	0.250	0.265	6.35	6.73
е	0.090	BSC	2.29	BSC
Н	0.370	0.410	9.40	10.41
L	0.055	0.070	1.40	1.78
L1	0.108 REF		2.74	REF
L2	0.020	BSC	0.51	BSC
L3	0.035	0.050	0.89	1.27
L4		0.040	-	1.01
ر <mark>ک</mark> رر	155,0ع		3.93	
STYLE 1:				

- PIN 1. BASE

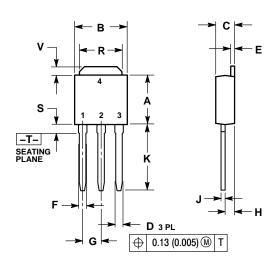
  - 2. COLLECTOR
    3. EMITTER
    4. COLLECTOR COLLECTOR
- **SOLDERING FOOTPRINT\***

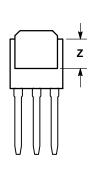


\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### PACKAGE DIMENSIONS

#### **IPAK** CASE 369D ISSUE C





- DIMENSIONING AND TOLERANCING PER
- ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.

	INCHES		MILLIN	ETERS
DIM	MIN	MAX	MIN	MAX
Α	0.235	0.245	5.97	6.35
В	0.250	0.265	6.35	6.73
С	0.086	0.094	2.19	2.38
D	0.027	0.035	0.69	0.88
Е	0.018	0.023	0.46	0.58
F	0.037	0.045	0.94	1.14
G	0.090 BSC		2.29	BSC
Н	0.034	0.040	0.87	1.01
J	0.018	0.023	0.46	0.58
K	0.350	0.380	8.89	9.65
R	0.180	0.215	4.45	5.45
S	0.025	0.040	0.63	1.01
٧	0.035	0.050	0.89	1.27
Z	0.155		3.93	

#### STYLE 1:

PIN 1. BASE

- 2. COLLECTOR
  - **EMITTER**
- COLLECTOR

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